

Features

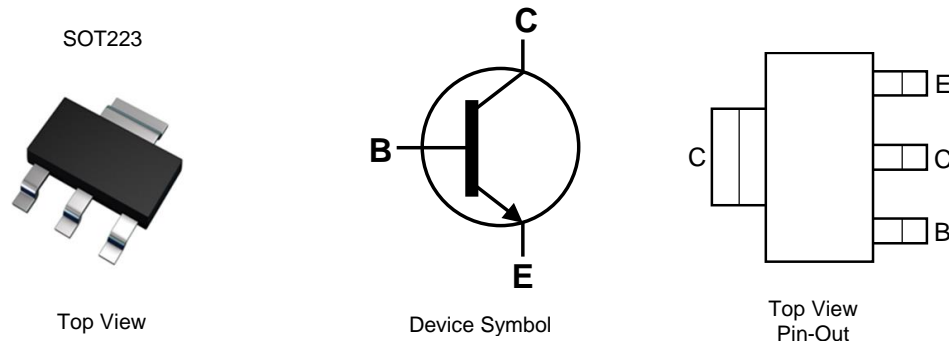
- $BV_{CEX} > 180V$
- $BV_{CEO} > 100V$
- $BV_{ECO} > 6V$
- $I_C = 3A$ High Continuous Current
- Low Saturation Voltage $V_{CE(sat)} < 100mV @ 1A$
- $R_{CE(sat)} = 85m\Omega$
- Complementary PNP Type: ZXTP19100CG
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound;
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 (Ⓢ)
- Weight: 0.112 grams (Approximate)

Applications

- PSU Start-Up Circuit
- DC-DC Converters
- Motor Drive
- Relay, Lamp and Solenoid Drive

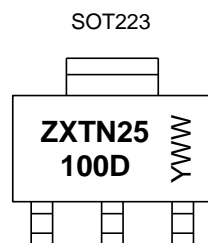


Ordering Information (Notes 4 & 5)

| Product | Compliance | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|----------------|------------|------------|--------------------|-----------------|-------------------|
| ZXTN25100DGTA | AEC-Q101 | ZXTN25100D | 7 | 12 | 1,000 |
| ZXTN25100DGQTA | Automotive | ZXTN25100D | 7 | 12 | 1,000 |

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



ZXTN25100D = Product Type Marking Code
 YWW = Date Code Marking
 Y or \bar{Y} = Last Digit of Year (ex: 5= 2015)
 WW or \bar{WW} = Week Code (01~53)

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--|------------------|-------|------|
| Collector-Base Voltage | V _{CBO} | 180 | V |
| Collector-Emitter Voltage (forward blocking) | V _{CEX} | 180 | V |
| Collector-Emitter Voltage | V _{CEO} | 100 | V |
| Emitter-Collector Voltage (reverse blocking) | V _{ECO} | 6 | V |
| Emitter-Base Voltage | V _{EBO} | 7 | V |
| Continuous Collector Current | I _C | 3 | A |
| Base Current | I _B | 1 | A |
| Peak Pulse Current | I _{CM} | 3.5 | A |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

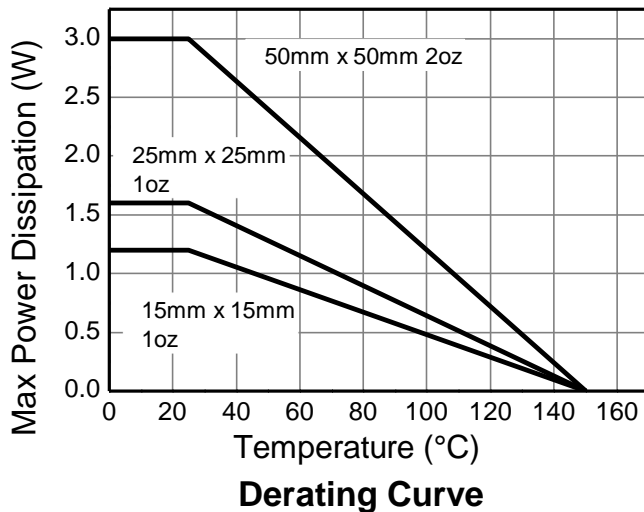
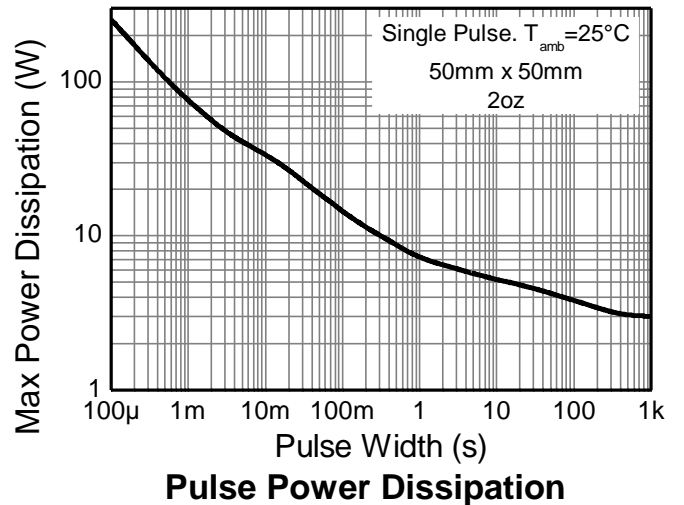
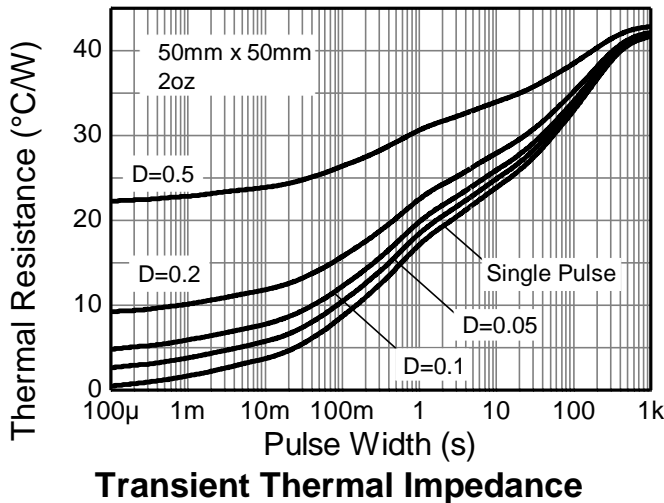
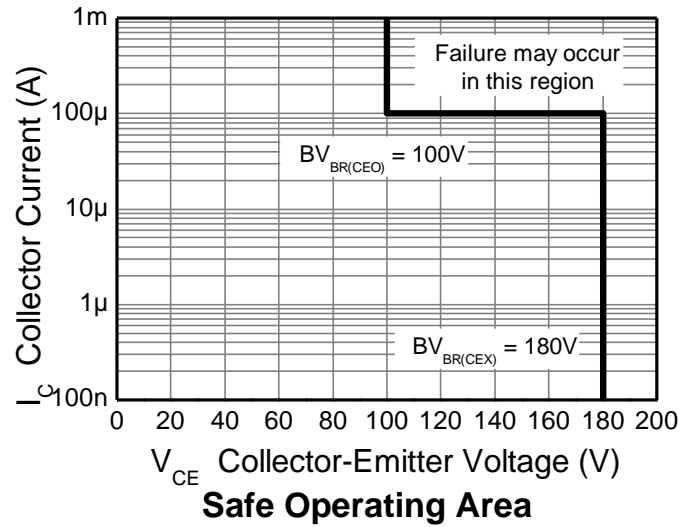
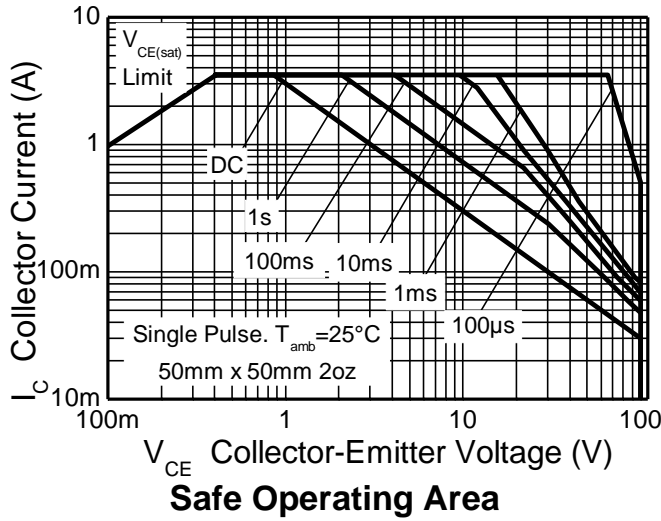
| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------------|
| Power Dissipation Linear Derating Factor | P _D | 1.2 | W mW/°C |
| | | 9.6 | |
| | | 1.6 | |
| | | 12.8 | |
| | | 3 | |
| Thermal Resistance, Junction to Ambient | R _{θJA} | 24 | °C/W |
| | | 5.3 | |
| | | 42 | |
| | | 104 | |
| Thermal Resistance, Junction to Lead | R _{θJL} | 78 | °C/W |
| | | 42 | |
| | | 23.5 | |
| Thermal Resistance, Junction to Solder Point | R _{θJS} | 16 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

ESD Ratings (Note 11)

| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | C |

- Notes:
- For a device mounted with the collector lead on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady-state.
 - Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
 - Same as Note 6, except the device is mounted on 50mm x 50mm 2oz copper.
 - Same as Note 8 measured at t<5 seconds.
 - Thermal resistance from junction to solder-point (at the end of the collector lead).
 - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

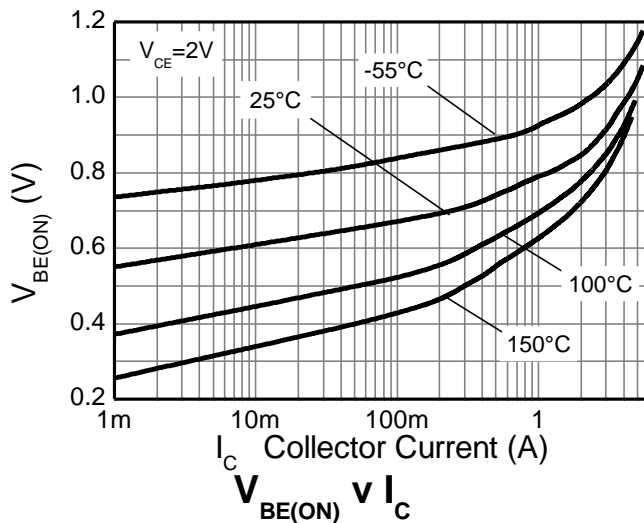
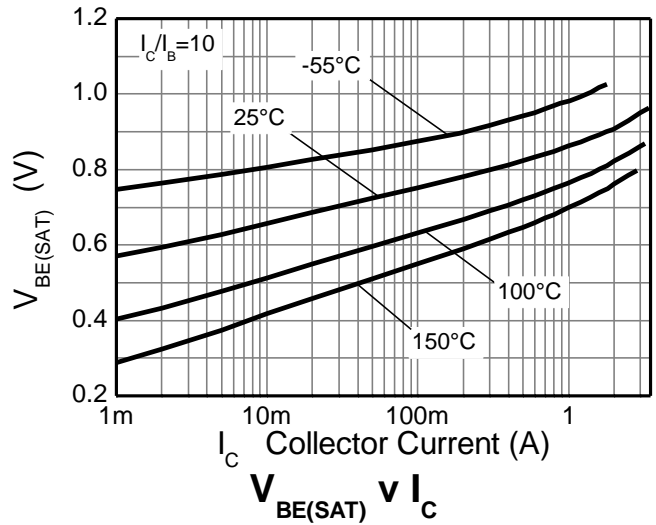
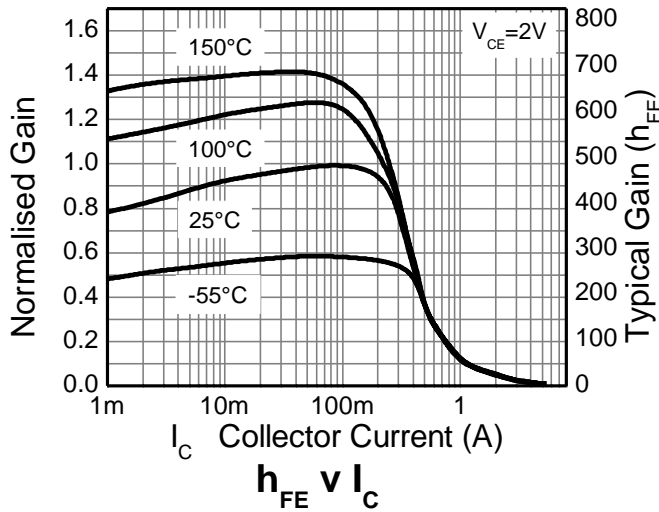
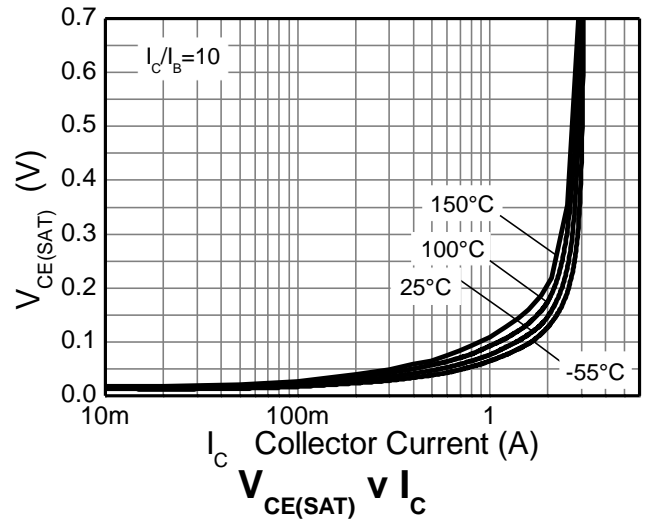
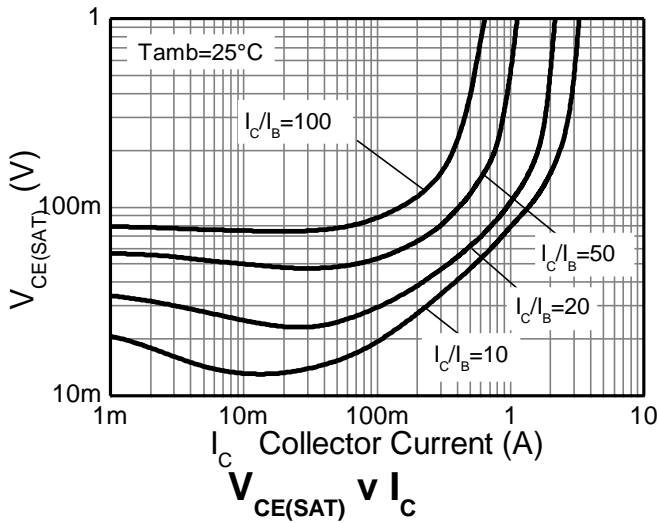


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|----------------------|-----|------|------|------|--|
| Collector-Base Breakdown Voltage | BV _{CBO} | 180 | 220 | – | V | I _C = 100μA |
| Collector-Emitter Breakdown Voltage (forward blocking) | BV _{CEX} | 180 | 220 | – | V | I _C = 100μA, R _{BE} < 1kΩ or -1V < V _{BC} > 0.25V |
| Collector-Emitter Breakdown Voltage (Note 12) | BV _{CEO} | 100 | 130 | – | V | I _C = 10mA |
| Emitter-Collector Breakdown Voltage (reverse blocking) | BV _{ECX} | 6 | 8.2 | – | V | I _C = 100μA, R _{BC} < 1kΩ or 0.25V < V _{BC} > -0.25V |
| Emitter-Collector Breakdown Voltage (reverse blocking) | BV _{EEO} | 6 | 8.7 | – | V | I _E = 100μA |
| Emitter-Base Breakdown Voltage | BV _{EBO} | 7 | 8.3 | – | V | I _E = 100μA |
| Collector Cut-Off Current | I _{CBO} | – | < 1 | 50 | nA | V _{CB} = 180V |
| | | – | – | 0.5 | μA | V _{CB} = 180V, T _A = 105°C |
| Collector-Emitter Cut-Off Current | I _{CEX} | – | – | 100 | nA | V _{CE} = 100V, R _{BE} < 1kΩ or -1V < V _{BC} > 0.25V |
| Emitter Cut-Off Current | I _{EBO} | – | < 1 | 50 | nA | V _{EB} = 5.6V |
| Collector-Emitter Saturation Voltage (Note 12) | V _{CE(sat)} | – | 120 | 170 | mV | I _C = 0.5A, I _B = 10mA |
| | | – | 80 | 100 | mV | I _C = 1A, I _B = 100mA |
| | | – | 215 | 345 | mV | I _C = 2.5A, I _B = 250mA |
| | | – | 200 | 500 | mV | I _C = 3A, I _B = 600mA |
| Base-Emitter Saturation Voltage (Note 12) | V _{BE(sat)} | – | 1020 | 1100 | mV | I _C = 3A, I _B = 600mA |
| Base-Emitter Turn-On Voltage (Note 12) | V _{BE(on)} | – | 905 | 1000 | mV | I _C = 3A, V _{CE} = 2V |
| DC Current Gain (Note 12) | h _{FE} | 300 | 450 | 900 | – | I _C = 10mA, V _{CE} = 2V |
| | | 120 | 170 | – | – | I _C = 0.5A, V _{CE} = 2V |
| | | 40 | 60 | – | – | I _C = 1A, V _{CE} = 2V |
| | | – | 10 | – | – | I _C = 3A, V _{CE} = 2V |
| Current Gain-Bandwidth Product (Note 12) | f _T | – | 175 | – | MHz | V _{CE} = 10V, I _C = 50mA, f = 100MHz |
| Input Capacitance (Note 12) | C _{ibo} | – | 154 | 250 | pF | V _{EB} = 0.5V, f = 1MHz |
| Output Capacitance (Note 12) | C _{obo} | – | 8.7 | 15 | pF | V _{CB} = 10V, f = 1MHz |
| Delay Time | t _d | – | 16.4 | – | ns | I _C = 500mA, V _{CC} = 10V, I _{B1} = -I _{B2} = 50mA |
| Rise Time | t _r | – | 115 | – | ns | |
| Storage Time | t _s | – | 763 | – | ns | |
| Fall Time | t _f | – | 158 | – | ns | |

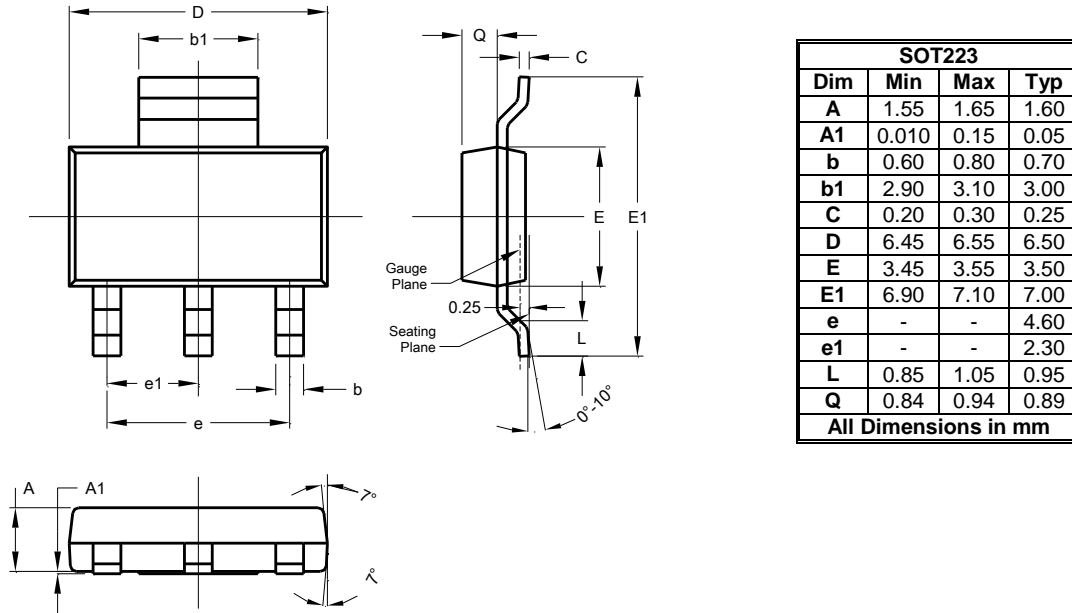
Note: 12. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



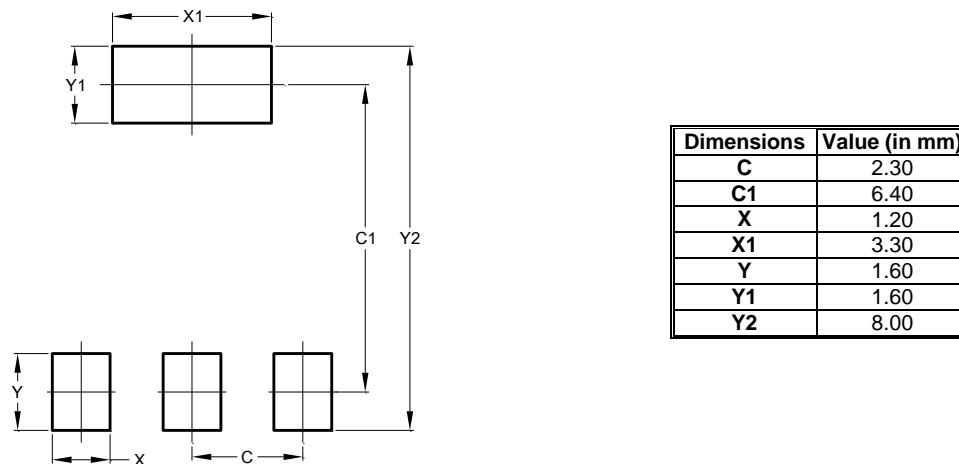
Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.

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